Power MOSFET, N-Channel, SUPERFET[®] III, Easy Drive, 650 V, 12 A, 260 m Ω

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SUPERFET III MOSFET Easy drive series helps manage EMI issues and allows for easier design implementation.

Features

- 700 V @ $T_J = 150^{\circ}C$
- Typ. $R_{DS(on)} = 222 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. $Q_g = 24 \text{ nC}$)
- Low Effective Output Capacitance (Typ. $C_{oss(eff.)} = 248 \text{ pF}$)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

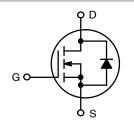
- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter



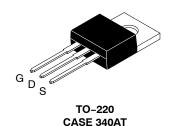
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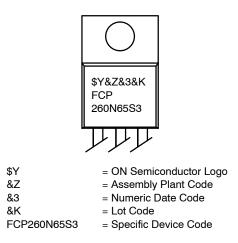
| V _{DSS} | R _{DS(ON)} MAX | I _D MAX |
|------------------|-------------------------|--------------------|
| 650 V | 260 mΩ @ 10 V | 12 A |



POWER MOSFET



MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

| Symbol | Parameter | | Value | Unit |
|-----------------------------------|--|-------------------------------------|-------------|------|
| V _{DSS} | Drain to Source Voltage | | 650 | V |
| V _{GSS} | Gate to Source Voltage | DC | ±30 | V |
| | | AC (f > 1 Hz) | ±30 | V |
| I _D | Drain Current | Continuous (T _C = 25°C) | 12 | Α |
| | | Continuous (T _C = 100°C) | 7.6 | |
| I _{DM} | Drain Current | Pulsed (Note 1) | 30 | А |
| E _{AS} | Single Pulsed Avalanche Energy (Note 2) | | 57 | mJ |
| I _{AS} | Avalanche Current (Note 1) | | 2.3 | А |
| E _{AR} | Repetitive Avalanche Energy (Note 1) | | 0.9 | mJ |
| dv/dt | MOSFET dv/dt | | 100 | V/ns |
| | Peak Diode Recovery dv/dt (Note 3) | | 20 | |
| PD | Power Dissipation | (T _C = 25°C) | 90 | W |
| | | Derate Above 25°C | 0.72 | W/°C |
| T _J , T _{STG} | Operating and Storage Temperature Range | | –55 to +150 | °C |
| ΤL | Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s | | 300 | °C |

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. $I_{AS} = 2.3 \text{ A}, R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$. 3. $I_{SD} \le 6 \text{ A}, \text{ di/dt} \le 200 \text{ A/}\mu\text{s}, V_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

| Symbol | Parameter | Value | Unit |
|-----------------------|---|-------|------|
| $R_{	extsf{	heta}JC}$ | Thermal Resistance, Junction to Case, Max. | 1.39 | °C/W |
| $R_{	hetaJA}$ | Thermal Resistance, Junction to Ambient, Max. | 62.5 | |

PACKAGE MARKING AND ORDERING INFORMATION

| Part Number | Top Marking | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|-------------|---------|----------------|-----------|------------|----------|
| FCP260N65S3 | FCP260N65S3 | TO-220 | Tube | N/A | N/A | 50 Units |

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Unit |
|--|--|--|-----|------|------|------|
| OFF CHARACT | ERISTICS | - | | | | |
| BV _{DSS} I | Drain to Source Breakdown Voltage | V_{GS} = 0 V, I_D = 1 mA, T_J = 25°C | 650 | | | V |
| | | V_{GS} = 0 V, I _D = 1 mA, T _J = 150°C | 700 | | | V |
| $\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$ | Breakdown Voltage Temperature Coefficient | $I_D = 1$ mA, Referenced to $25^{\circ}C$ | | 0.66 | | V/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$ | | | 1 | μA |
| | | V_{DS} = 520 V, T_{C} = 125 $^{\circ}C$ | | 0.77 | | |
| I _{GSS} | Gate to Body Leakage Current | $V_{GS} = \pm 30$ V, $V_{DS} = 0$ V | | | ±100 | nA |
| ON CHARACTE | ERISTICS | | - | - | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{GS} = V_{DS}, I_D = 1.2 \text{ mA}$ | 2.5 | | 4.5 | V |
| R _{DS(on)} | Static Drain to Source On Resistance | V _{GS} = 10 V, I _D = 6 A | | 222 | 260 | mΩ |
| 9 _{FS} | Forward Transconductance | V _{DS} = 20 V, I _D = 6 A | | 7.4 | | S |
| YNAMIC CHA | RACTERISTICS | | - | - | | |
| C _{iss} | Input Capacitance | V_{DS} = 400 V, V_{GS} = 0 V, f = 1 MHz | | 1010 | | pF |
| Coss | Output Capacitance | | | 25 | | pF |
| C _{oss(eff.)} | Effective Output Capacitance | V_{DS} = 0 V to 400 V, V_{GS} = 0 V | | 248 | | pF |
| C _{oss(er.)} | Energy Related Output Capacitance | V_{DS} = 0 V to 400 V, V_{GS} = 0 V | | 33 | | pF |
| Q _{g(tot)} | Total Gate Charge at 10 V | V _{DS} = 400 V, I _D = 6 A, V _{GS} = 10 V (Note 4) | | 24 | | nC |
| Q _{gs} | Gate to Source Gate Charge | | | 6.1 | | nC |
| Q _{gd} | Gate to Drain "Miller" Charge | | | 9.7 | | nC |
| ESR | Equivalent Series Resistance | f = 1 MHz | | 8.7 | | Ω |
| WITCHING CH | IARACTERISTICS | | | | | |
| t _{d(on)} | Turn-On Delay Time | $V_{DD} = 400 \text{ V}, \text{ I}_{D} = 6 \text{ A}, \\ V_{GS} = 10 \text{ V}, \text{ R}_{g} = 4.7 \Omega \\ \text{(Note 4)}$ | | 18 | | ns |
| t _r | Turn-On Rise Time | | | 18 | | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 49 | | ns |
| t _f | Turn-Off Fall Time | | | 12 | | ns |
| OURCE-DRAI | N DIODE CHARACTERISTICS | | | | | |
| ۱ _S | Maximum Continuous Source to Drain Diode Forward Current | | | | 12 | Α |
| I _{SM} | Maximum Pulsed Source to Drain Diode Forward Current | | | | 30 | Α |
| V _{SD} | Source to Drain Diode Forward Voltage | $V_{GS} = 0 V$, $I_{SD} = 6 A$ | | | 1.2 | V |
| t _{rr} | Reverse Recovery Time | $V_{DD} = 400 \text{ V}, \text{ I}_{SD} = 6 \text{ A},$ | | 251 | | ns |
| Q _{rr} | Reverse Recovery Charge | — dI _F /dt = 100 A/μs | | 3.4 | | μC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

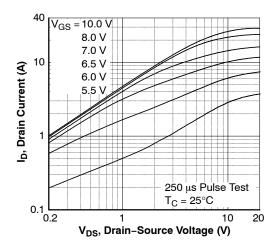
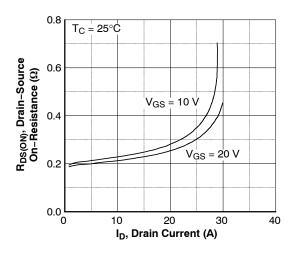
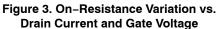


Figure 1. On–Region Characteristics





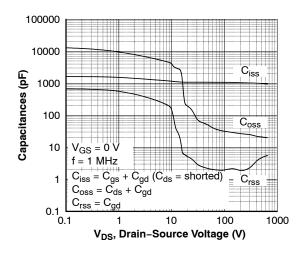


Figure 5. Capacitance Characteristics

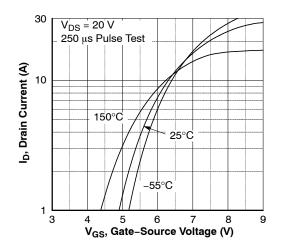
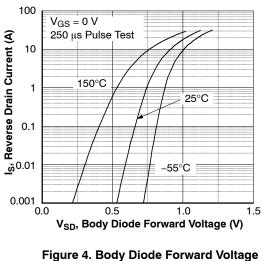
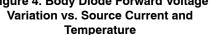


Figure 2. Transfer Characteristics





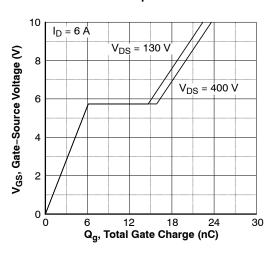
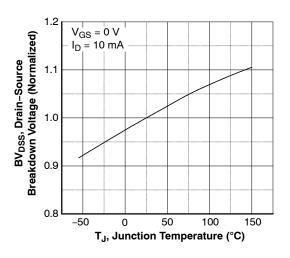
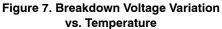


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)





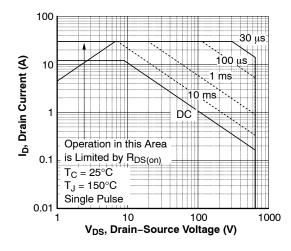


Figure 9. Maximum Safe Operating Area

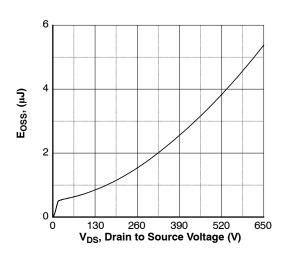


Figure 11. E_{OSS} vs. Drain to Source Voltage

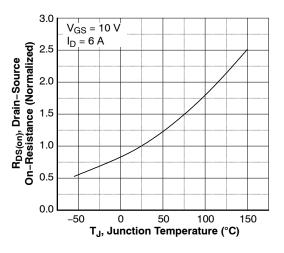


Figure 8. On–Resistance Variation vs. Temperature

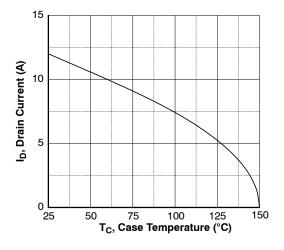


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

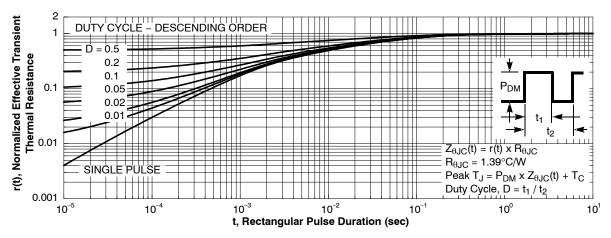
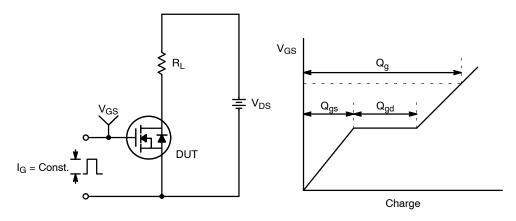


Figure 12. Transient Thermal Response Curve





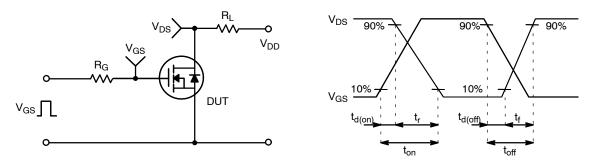
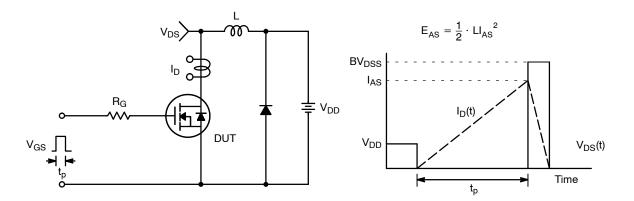


Figure 14. Resistive Switching Test Circuit & Waveforms





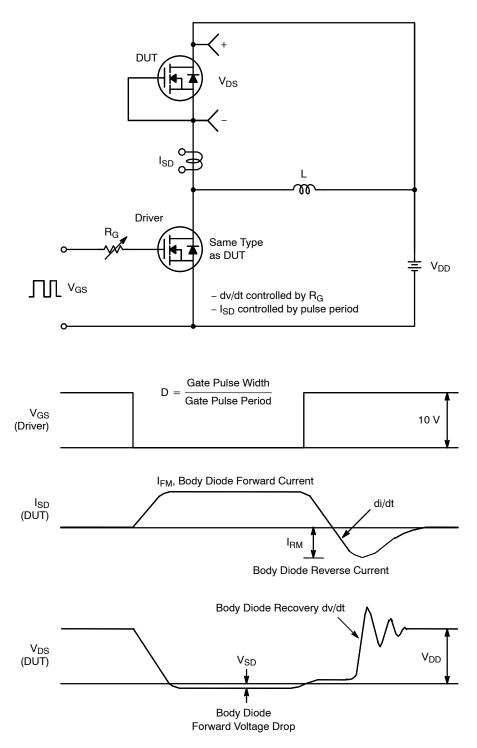
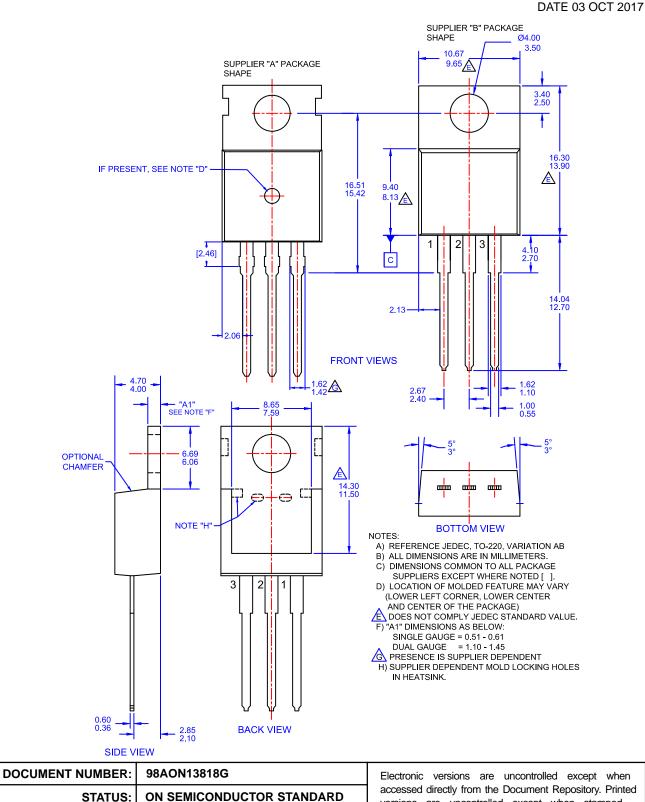


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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